

0603HV

Fast-acting chip fuses



Product features

- 0603 (1608 metric) compact design utilizes less board space
- Rapid interruption of excessive current
- · Compatible with reflow and wave solder
- Rugged ceramic and glass construction
- · Excellent environmental integrity
- · One time positive disconnect
- High breaking capacity up to 63 V
- Mositure sensitivity level (MSL): 1

Applications

Secondary circuit protection

- I/O Switch modules
- Printers
- Laptop, notebook, netbook
- Tablets, e-readers
- · Flat panel displays
- High definition television (HDTV)
- Gaming console systems
- Handheld/portable equipment
- Mobile device chargers

Agency information

• UL Recognized File: File E19180



Environmental compliance







• Values less than 1 A are not lead free

Ordering

• Use ordering codes (see page 3 for details)

Packaging prefixes

TR- (5,000 parts in paper tape on a 178 mm (7") reel)



Electrical characteristics

Amp Rating	% of Amp Rating	Opening Time
500 mA – 1.5 A	100%	4 hours minimum
500 mA – 1.5 A	200%	60 seconds maximum

Product specifications

Part Number ⁵	Current rating (A)	Voltage rating (Vdc)	Interrupting rating ¹ (A)	Typical DC cold resistance² (Ω)	Typical pre-arcing ³ I ² t (A ² s)	Typical voltage drop (V)	Part marking
0603HV500-R	0.5	63	50	1.025	0.0019	0.60	F
0603HV750-R	0.75	63	50	0.51	0.003	0.50	G
0603HV1-R	1	63	50	0.15	0.007	0.211	Н
0603HV1.25-R	1.25	63	50	0.132	0.008	0.201	J
0603HV1.5-R	1.5	63	50	0.086	0.0319	0.138	K

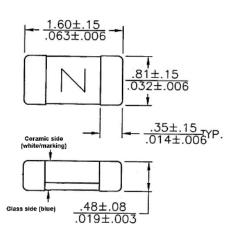
- 1. DC interrupting rating measured at rated voltage, time constant less than 50 microseconds, battery source
- 2. DC cold resistance measured at <10% of rated current
- 3. Typical pre-arcing I²t measured with a battery bank at rated dc voltage, 10x-rated current, not to exceed IR, time constant of calibrated circuit less than 50 microsecond
- 4. Typical voltage drop measured at rated current after temperature stabilizes
- 5. Part Number Definition: 0603HVxxx-R

0603HV = Product code and size

xxx - Ampere rating

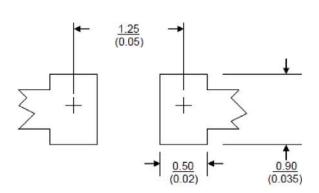
-R suffix = RoHS complaint

Dimensions-mm

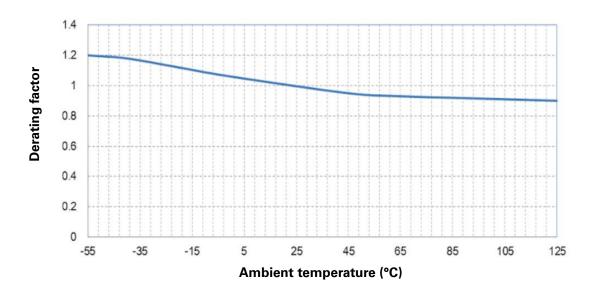


Fuse to be installed with ceramic side up (white/marking)

Recommended pad layout



Temperature derating curve



Environmental data

Operating temperature: -55 °C to +125 °C (with derating)

Storage temperature (component): -55 °C to +125 °C

Terminal strength test: Force of 1.8 kg for 60 seconds (no physical evidence of mechanical or physical damage, change in resistance < 5%

Ordering codes

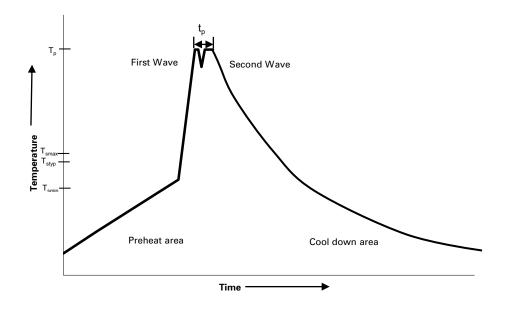
The ordering code is the part number replacing the "" with a "-" plus adding the packaging preffix.

Packaging prefix

TR- (5,000 parts in paper tape on a 178 mm (7") reel)

	Ordering code	
Part Number	TR- option	
0603HV500-R	TR-0603HV500-R	
0603HV750-R	TR-0603HV750-R	
0603HV1-R	TR-0603HV1-R	
0603HV1.25-R	TR-0603HV1-25-R	
0603HV1.5-R	TR-0603HV1-5-R	

Wave solder profile



Reference EN 61760-1:2006

Profile feature		Standard SnPb solder	Lead (Pb) free solder
Preheat	• Temperature min. (T _{smin})	100 °C	100 °C
	• Temperature typ. (T _{styp})	120 °C	120 °C
	• Temperature max. (T _{smax})	130 °C	130 °C
	Time (T _{smin} to T _{smax}) (t _s)	70 seconds	70 seconds
Δ preheat to	max Temperature	150 °C max.	150 °C max.
Peak tempera	ature (Tp)*	235 °C − 260 °C	250 °C − 260 °C
Time at peak	temperature (t _p)	10 seconds max 5 seconds max each wave	10 seconds max 5 seconds max each wave
Ramp-down r	ate	~ 2 K/s min ~3.5 K/s typ ~5 K/s max	~ 2 K/s min ~3.5 K/s typ ~5 K/s max
Time 25°C to	25°C	4 minutes	4 minutes

Manual solder

+350 °C (4-5 seconds by soldering iron), generally manual/hand soldering is not recommended

Solder reflow profile

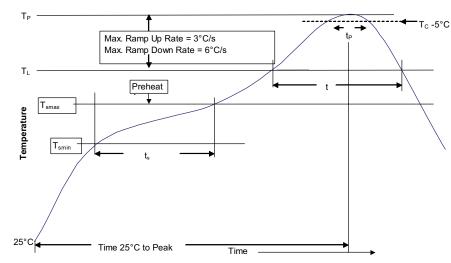


Table 1 - Standard SnPb solder (T_C)

Package thickness	Volume mm3 <350	Volume mm3 ≥350
<2.5 mm)	235 °C	220 °C
≥2.5 mm	220 °C	220 °C

Table 2 - Lead (Pb) free solder (T_C)

Package thickness	Volume mm³ <350	Volume mm³ 350 - 2000	Volume mm³ >2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 – 2.5 mm	260 °C	250 °C	245 °C
>2.5 mm	250 °C	245 °C	245 °C

Reference J-STD-020

Profile feature	Standard SnPb solder	Lead (Pb) free solder	
Preheat and soak • Temperature min. (T _{smin})	100 °C	150 °C	
Temperature max. (T _{smax})	150 °C	200 °C	
• Time (T _{smin} to T _{smax}) (t _s)	60-120 seconds	60-120 seconds	
Ramp up rate T_L to T_p	3 °C/ second max.	3 °C/ second max.	
Liquidous temperature (T_L) Time (t_L) maintained above T_L	183 °C 60-150 seconds	217 °C 60-150 seconds	
Peak package body temperature (Tp)*	Table 1	Table 2	
Time (t _p)* within 5 °C of the specified classification temperature (T _C)	20 seconds*	30 seconds*	
Ramp-down rate (T _p to T _L)	6 °C/ second max.	6 °C/ second max.	
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.	

^{*} Tolerance for peak profile temperature (Tp) is defined as a supplier minimum and a user maximum.

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